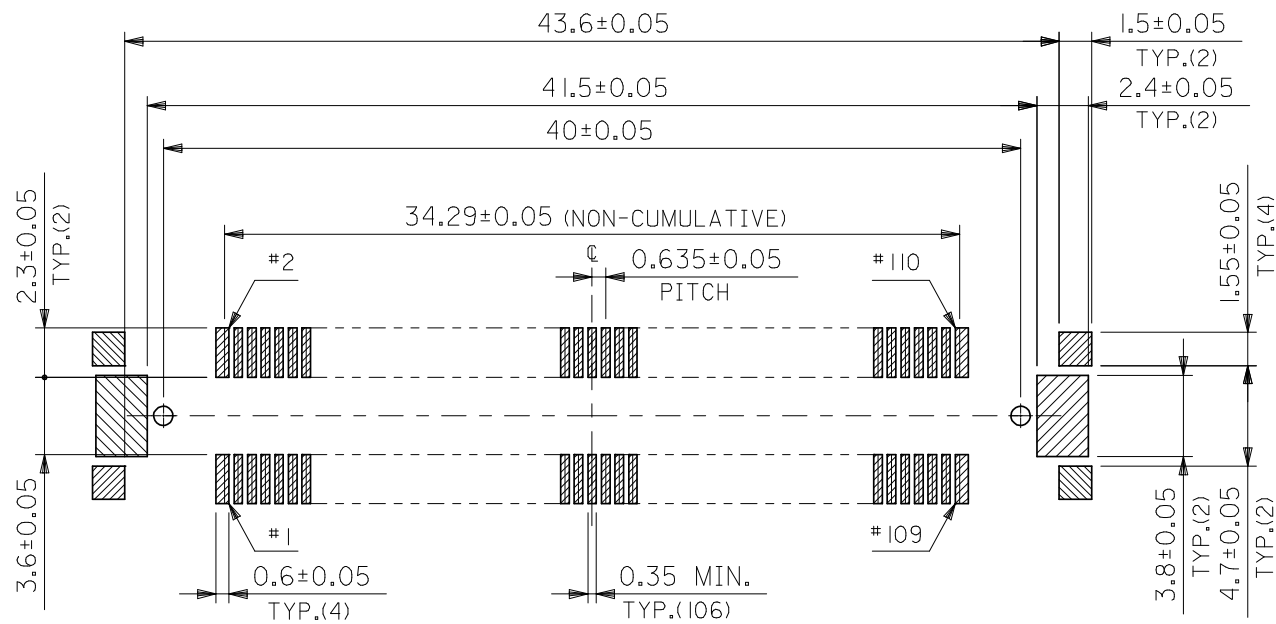


NOTES

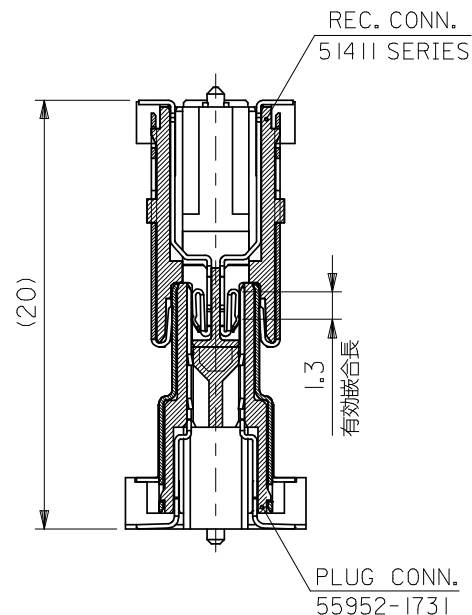
- 材質
MATERIAL
ハウジング : ガラス入り LCP、黒色、UL94V-0
HOUSING : GLASS FILLED LIQUID CRYSTAL POLYMER, BLACK, UL94V-0
ターミナル : 銅合金
TERMINAL : COPPER ALLOY
シールド : 鉄鋼
SHIELD : STEEL
ネイル : 銅合金
NAIL : COPPER ALLOY
- メッキ仕様
PLATING
ターミナル : シールド
TERMINAL : ニッケル下地 錫メッキ
接点部 : 金メッキ
CONTACT AREA : GOLD
半田付け部 : 錫メッキ
SOLDER TAIL AREA : TIN
下地メッキ : ニッケルメッキ
UNDER-PLATING : NICKEL
ニッケル下地 錫メッキ
TIN OVER NICKEL PLATING
ネイル
NAIL
ニッケル下地 錫メッキ
TIN OVER NICKEL PLATING
- テールとネイルの平坦度 : 0.1 MAX.
COPLANARITY : 0.1 MAXIMUM
- 本製品は55952-1131の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55952-1131.

TRAY	55952-1731	110
PACKAGING	MATERIAL NO.	CIRCUITS

REVISED EC NO: J2008-3221 DRW: HAYASHI 2008/03/26 CHKD: THARUYAMA 2008/03/26 APPR: NUKITA 2008/03/26	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY YSAKIYAMA	DATE 04/02/18	TITLE 0.635 B/B SHIELD TYPE PLUG ASSY -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY MSASAO	DATE 04/02/18				
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/18	MOLEX INCORPORATED			
	ANGULAR	±1 °	MATERIAL NO.	DOCUMENT NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-55952-010				



推奨基板レイアウト
RECOMMENDED P.C.B LAYOUT



REVISED EC NO: J2008-3221 DRW:HYAJIMA 2008/03/26 CHKD: 2008/03/26 APPR: NUKITA 2008/03/26	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY YSAKIYAMA	DATE 04/02/18	TITLE 0.635 B/B SHIELD TYPE PLUG ASSY -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY MSASAO	DATE 04/02/18				
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/18	MOLEX INCORPORATED			
	ANGULAR ±1 °		MATERIAL NO.	DOCUMENT NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET No.1		SD-55952-010		2 OF 2		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						